

Low Profile Miniature Crystal

9.6MHz to 160MHz

FEATURES

- Low profile, hermetically sealed ceramic package
- Excellent ageing characteristics
- High shock resistance
- Full military testing available
- Available with glass or ceramic lid
- Custom designs available

DESCRIPTION

CX-2 AT crystals are designed in a rugged, ceramic package. Due to its robust design this crystal has gained wide acceptance in the industry.

SPECIFICATION

Specifications stated are typical at 25°C unless otherwise indicated. Specifications may change without notice.

Fundamental Frequency:	10.0MHz	32.0MHz	155.52MHz
Motional Resistance R (Ω):	60	20	50
Motional Capacitance C1 (fF):	2.8	7.8	0.5
QualityFactor Q (k):	95	36	41
Shunt Capacitance C0 (pF):	1.4	2.4	3.2

Calibration Tolerance¹: $A = \pm 0.01\% (\pm 100 ppm)$

 $B = \pm 0.1\%$ $C = \pm 1\%$

Load Capacitance: 20pF (Unless specified by

customer)

Drive Level: 500µW maximum

Temperature Stability²

Commercial -10 ~ +60°C: from ±10ppm from ±20ppm from ±30ppm from ±30ppm
Ageing, first year: 5ppm maximum
Shock, survival: 3,000g, 0.2ms, ½ sine
Vibration, survival: 20g, 10~2000Hz random

Operating Temperature Range

Commercial: -10° to +70°C Industrial: -40° to +85°C Military: -55 to +125°C ture Ranae: -55° to +125°C

Storage Temperature Range: -55° to +125°C

Maximum Process Temperature: See package handling notes

Note: The characteristics of the frequency temperature stability follow

that of AT-Cut Thickness Shear mode.

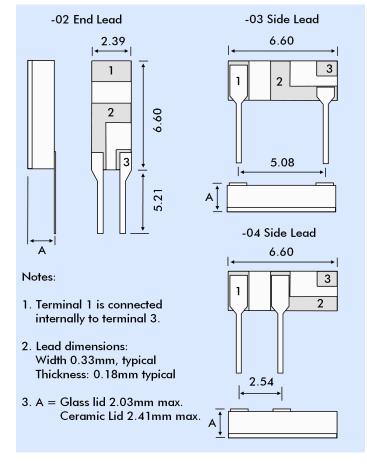
1. Tighter tolerances available.

2. Does not include calibration tolerance.

3. Higher shock version available

OUTLINE & DIMENSIONS





PACKAGE HANDLING

The CX crystal is hermetically sealed in a ceramic package. Normal handling and soldering precautions for small, low thermal mass parts are adequate when installing or testing CX crystals. CX crystals may be wave soldered with proper precaution taken to avoid desoldering the leads. A slow machine rate or too high a pre-heat temperature or solder bath temperature may damage the crystals. Lead to package solder interface temperature should not exceed 175°C, glass lid to package seal rim temperature should not exceed 210°C. If the seal rim reaches temperatures above the maximum specified, the package may lose its hermeticity. Loss of hermeticity results in a frequency decrease and motional resistance increase.

HOW TO ORDER CX-2 LEADED CRYSTALS

